

Appl. No. 09/909,597
Amdt. Dated
Reply to Office Action of July 12, 2005

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A package for containing a semiconductor element comprising:

a housing containing a semiconductor element; and

a pair of positioning holes and a pair of attaching holes respectively provided at opposed side portions of said housing;

wherein a line between said pair of positioning holes and a line between said pair of attaching holes intersect with each other substantially at a center of said package and further wherein the line between the positioning holes is skewed with respect to each of four primary side walls of the housing and the line between the attaching holes is skewed with respect to each of the four primary side walls such that the line between the positioning holes and the line between the attaching holes are each neither parallel nor perpendicular to any of the primary side walls,

and further wherein the line between said pair of positioning holes is a straight line between centers of the positioning holes and is skewed with respect to each of four primary side walls of the housing and the line between said pair of attaching holes is a straight line between the centers of the attaching holes and is skewed with respect to each of four primary side walls such that the line between the positioning holes and the line between the attaching holes are each neither parallel nor perpendicular to any of the primary side walls, and neither line is located at a center line of the device which is perpendicular to the primary side walls a

Appl. No. 09/909,597
Amdt. Dated
Reply to Office Action of July 12, 2005

~~space between the positioning hole and the attaching hole at one side is narrower than a diameter of either of the two holes.~~

2. (Original) The package according to claim 1:

wherein said semiconductor element is a solid-state imaging element.

3. (Currently Amended) A semiconductor device comprising:

a semiconductor element;

a housing containing said semiconductor element; and

a pair of positioning holes and a pair of attaching holes respectively provided at opposed side portions of said housing;

wherein a line between said pair of positioning holes and a line connecting said pair of attaching holes are intersected with each other substantially at a center of said package,

and further wherein the line between said pair of positioning holes is a straight line between centers of the positioning holes and is skewed with respect to each of four primary side walls of the housing and the line between said pair of attaching holes is a straight line between the centers of the attaching holes and is skewed with respect to each of four primary side walls such that the line between the positioning holes and the line between the attaching holes are each neither parallel nor perpendicular to any of the primary side walls, and neither line is located at a center line of the device which is perpendicular to the primary side walls a
~~space between the positioning hole and the attaching hole at one side is narrower than a diameter of either of the two holes .~~

Appl. No. 09/909,597
Amdt. Dated
Reply to Office Action of July 12, 2005

4. (Original) The semiconductor device according to claim 3,
wherein said semiconductor element is a solid-state imaging element.

5. (Currently Amended) A semiconductor device comprising:
a semiconductor element;
a housing containing said semiconductor element,
a pair of attaching holes and a pair of positioning holes respectively provided at
opposed side portions of said housing at a surface of said package; and
a transparent member for sealing said semiconductor element in said recess portion;
wherein said surface of said package is made to be higher than a top surface of said
transparent member.

and further wherein a line between said pair of positioning holes is a straight line
between centers of the positioning holes and is skewed with respect to each of four primary
side walls of the housing and a line between the pair of attaching holes is a straight line
between the centers of the attaching holes and is skewed with respect to each of four primary
side walls such that the line between the positioning holes and the line between the attaching
holes are each neither parallel nor perpendicular to any of the primary side walls, and neither
line is located at a center line of the device which is perpendicular to the primary side walls a
space between the positioning hole and the attaching hole at one side is narrower than a
diameter of either of the two holes.

6. (Original) The semiconductor device according to claim 5,
wherein said semiconductor element is a solid-state imaging element.

Appl. No. 09/909,597
Amdt. Dated
Reply to Office Action of July 12, 2005

7. (Currently Amended) A package containing a semiconductor element comprising:

a housing containing a semiconductor element; and

a pair of positioning holes and a pair of attaching holes respectively provided at opposed side portions of said housing;

wherein a line between said pair of positioning holes and a line between said pair of attaching holes intersect with each other substantially at a center of said package and further wherein the line between the positioning holes is skewed with respect to each of four primary side walls of the housing and the line between the attaching holes is skewed with respect to each of the four primary side walls such that the line between the positioning holes and the line between the attaching holes are each neither parallel nor perpendicular to any of the primary side walls,

and further wherein the package is generally rectangular in shape and one positioning hole and one attaching hole is located on a first side of the package, and the second positioning hole and the second attaching hole are located on the opposite side such that the positioning holes are diametrically opposed in generally opposite quadrants of the package and the attaching holes are diametrically opposed in opposite quadrants of the package and a line generally bisecting the package in a central portion thereof separates the positioning holes and attaching holes, wherein the line between said pair of positioning holes is a straight line between centers of the positioning holes and is skewed with respect to each of four primary side walls of the housing and the line between said pair of attaching holes is a straight line between the centers of the attaching holes and is skewed with respect to each of

Appl. No. 09/909,597
Amdt. Dated
Reply to Office Action of July 12, 2005

four primary side walls such that the line between the positioning holes and the line between the attaching holes are each neither parallel nor perpendicular to any of the primary side walls, and neither line is located at a center line of the device which is perpendicular to the primary side walls.

8 (New) A semiconductor device comprising:

a semiconductor element;

a housing containing said semiconductor element, the housing being comprised of two pairs of generally parallel primary side walls, the primary side walls being substantially mutually perpendicular, and each defining one of the largest four boundaries of said housing; and

a pair of positioning holes and a pair of attaching holes, one member of each pair of positioning holes and attaching holes being respectively provided at one of said opposed primary side walls of said housing;

wherein a line bisecting substantially a center of the housing is perpendicular to each of the primary side walls at which the positioning holes and attaching holes are located, each of the positioning holes and attaching holes being located at a portion of the sidewall on a side of the line bisecting substantially the center of the housing such that no portion of any positioning hole or attaching hole crosses the line and none of the positioning holes or attaching holes shares a same side of a primary side wall.

Appl. No. 09/909,597
Amdt. Dated
Reply to Office Action of July 12, 2005

9 (New) A semiconductor device comprising:

a semiconductor element;

a housing containing said semiconductor element, the housing being comprised of two pairs of generally parallel primary side walls, the primary side walls being substantially mutually perpendicular, and each defining one of the largest four boundaries of said housing; and

a pair of positioning holes and a pair of attaching holes, one member of each pair of positioning holes and attaching holes being respectively provided at one of said opposed primary side walls of said housing;

wherein a diameter of an attaching hole at a first primary side wall is defined to be a dimension a

a diameter of a positioning hole at the first primary side wall is defined to be a dimension c

a shortest interval between the attaching hole and the positioning hole is a dimension b and a shortest distance from the positioning hole at the first primary side wall and its closest intersection with an adjacent primary side wall is a dimension d,

and wherein the length of the first primary side wall is substantially equal to:

$a+b+c+(dx^2)$.